APPLICA	BLE STAN	DARD										
Operating te range				85 °C	range)			-10 °C to 50 °C (packed condition			
RATING	Voltage		30 V AC /	DC	humi	dity rang		Relative humidity 90%MAX(not			dewed)	
	Current		0.20 A		Appli	cable ca	able		t=0.12±0.02mm, gold	platin	g	
			SPE	CIFIC	OITA	NS		•				
IT	EM		TEST METHOD			<u> </u>	RF	OUI	REMENTS	QT	АТ	
CONSTR			1201 WE11102					ΨΟ.	I COMPANY	α.	1 /	
		Visually a	nd by measuring instrume	ent.		Accord	ling to draw	vina.		×	×	
Marking		Confirmed				(note				×	×	
	ICAL CHA											
Voltage proof						No flas	hover or h	reak	down	×		
Insulation resistance		90 V AC for 1 min. 100 V DC.				No flashover or breakdown. 50 MΩ MIN.				+	×	
risulation res	Sistance	100 V DC	•			30 IVIS2	IVIIIN.			×	×	
Contact resistance		AC 20 mV MAX (1KHz), 1 mA.			200 mΩ MAX. Including FPC bulk resistance (L=8mm)				×	×		
MECHAN	IICAL CHA	RACTE	RISTICS			moraan	119 1 1 0 5 4		olotarioo (E olilli)			
Vibration	HOAL OH		y 10 to 55 Hz, half ampliti	ude 0.75 m	nm.	① No	electrical d	lisco	ntinuity of 1 us	×	Τ_	
		for 10 cyc	eles in 3 axial directions.	0.70 11	,	 No electrical discontinuity of 1 μs. Contact resistance: 200 mΩ MAX. 				^		
Shock		981 m/s ² , duration of pulse 6 ms at 3 times in 3 both axial directions.				No damage, crack and looseness of parts.			×	_		
Mechanical o	peration	10 times insertions and extractions.				 Contact resistance: 200 mΩ MAX. No damage, crack and looseness of parts. 			×	_		
FPC retention	n force	Measured by applicable FPC. (thickness of FPC shall be t=0.12mm at initial condition)			Direction of insertion: (0.15 × n)+0.7N MIN(note3) (n: Number of contacts)			×	-			
ENVIRON	MENTAL		ACTERISTICS			l						
Corrosion sal			at 35±2°C, 5% salt wate	r spray for	· 96 h.	Contac	t resistanc	e: 20	00 mΩ MAX.	×	-	
Rapid change of temperature		Temperature -55 \rightarrow +15 to +35 \rightarrow +85 \rightarrow +15 to +35 $^{\circ}$ C Time 30 \rightarrow 2 to 3 \rightarrow 30 \rightarrow 2 to 3 min Under 5 cycles.			 Contact resistance: 200 mΩ MAX. Insulation resistance: 50 MΩ MIN. No damage, crack and looseness of parts. 			×	-			
Damp heat (steady state)		Exposed at 40±2°C, Relative humidity 90 to 95 %, 96 h.					aamage, e		and issuential or parter	×	-	
Damp heat,cyclic		Exposed at -10 to +65°C, Relative humidity 90 to 96 %, 10 cycles, total 240 h.			 Contact resistance: 200 mΩ MAX. Insulation resistance: 1 MΩ MIN. (at high humidity) Insulation resistance: 50 MΩ MIN. (at dry) 				×	_		
					No damage, crack and looseness of parts.							
Dry heat		Exposed	cposed at 85±2°C, 96 h.			① Contact resistance: 200 mΩ MAX.				×	-	
Cold		Exposed	xposed at -55±3°C, 96 h.			② No damage, crack and looseness of parts.				×	—	
Sulphur dioxide [JIS C 60068-2-42]		Relative I	cposed at 40±2°C, elative humidity 80±5% 5±5 ppm for 96 h.			Contact resistance: 200 mΩ MAX.				×	1-	
Hydrogen sulphide [JIS C 60068-2-43] F		Exposed Relative I	Exposed at 40±2°C, Relative humidity 80±5%, 10 to 15 ppm for 96 h.							×	<u> </u>	
COUN	T DE			DESIG	GNED CHECKED			DATE				
<u>/0\</u>												
REMARK						APPRO				17.0	02. 21	
				CHECKED			YH. MICHIDA	17.0	02. 21			
			DESIGNED		ĒD	HY. YAMAZAKI	AMAZAKI 17. 0					
Unless otherwise specified, refer to IEC 60512.				DRAWN RK. OGASAWARA			17. 0	02. 20				
· · · · · · · · · · · · · · · · · · ·			DF	PRAWING NO. ELC-375451-0			0-00	0				
	LRS SPECIFICATION SHEET PART											
нs	SI	PECIFI	CATION SHEET		PART	NO.		FH6	64MA-**S-0. 25SH	W		

SPECIFICATIONS								
ITEM	TEST METHOD	REQUIREMENTS	QT	АТ				
Solderability	Soldered at solder temperature, 245±3°C for immersion duration, 3±0.3 sec.	A new uniform coating of solder shall cover a minimum of 95% of the surface being immersed.	×	_				
Resistance to soldering heat	1) Reflow soldering: Peak TMP. 250°C MAX. Reflow TMP. over 230°C within 60 sec. Number of allowed reflow cycles 2 times. 2) Soldering irons: TMP. 350±10°C for 5±1 sec.	No deformation of case of excessive looseness of the terminals. (<i>note 4</i>)	×	_				

(note1)

This is a top contact point connector with back flip lock system.

(note2)

Do not close the actuator before inserting FPC even after the connector is mounted onto a PCB.

Closing the actuator without FPC could make the contact gap smaller, which increases the FPC insertion force.

(note3)

Stabilize the FPC to PCB or something fixed, if pull-up or pull-down force is exepected to be applied to the FPC.

There is a case which the FPC retention force doesn't fullfill the specification depending on the FPC specification.

(note4)

Blisters which may be generated on the housing do not affect product performance.

Note Q	Qualification Test AT:Assurance Test X:Applicable Test	DRAWIN	NG NO.	ELC-375451-00-00			
R	SPECIFICATION SHEET	PART NO.	PART NO. FH64MA-**S-0. 25SH			HW	
10	HIROSE ELECTRIC CO., LTD.	CODE NO		CL580	Δ	2/2	